SMTA Press Release

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SMTA Announces Program for 2026 Ultra High Density Interconnect (UHDI) Symposium

MINNEAPOLIS, Minn. **--** The SMTA is excited to announce the technical program for the 3rd annual Ultra High Density Interconnect Symposium which takes place on April 9, 2026 in Avondale, Arizona, USA.

The program covers advancements in Ultra HDI across defense applications, fabrication technologies, materials, assembly processes, test development, research initiatives, and collaboration across the electronics manufacturing ecosystem.

This event sets the stage for researchers, engineers, designers and academia to address the complexities and innovations reshaping the world of Ultra HDI technology, which is producing printed circuit boards and semiconductors with lines and spaces well below 50 microns.

The City of Avondale is a proud partner of this event. Additional sponsorship opportunities are still available for this event. View more details online.

If there are any questions, please call +1-952-920-7682 or email tara@smta.org. For more information, visit https://smta.org/mpage/uhdi.

SMTA - A Global Association Working at a Local Level
The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

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